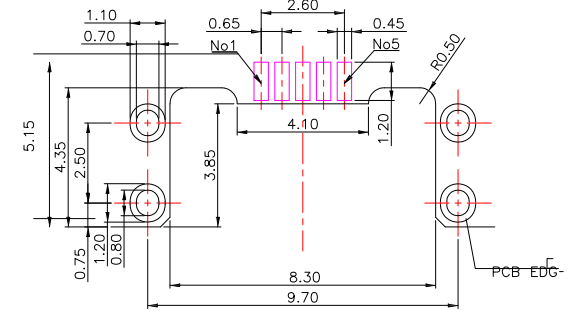
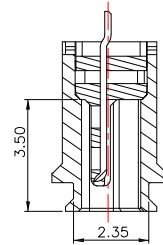
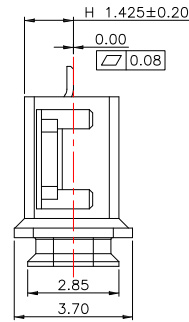
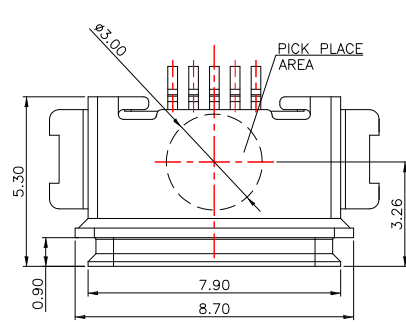
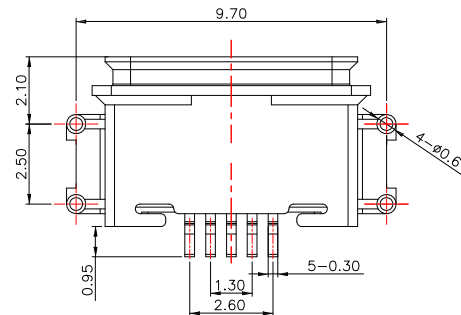
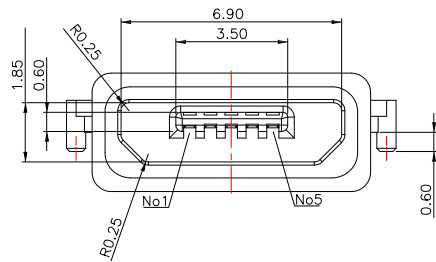


IPX7



P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP11-x-S382

鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"

NOTES:

MATERIAL:

1.1 HOUSING: HIGH-TEMP

1.2 CONTACT: COPPER ALLOY

1.3 SHELL: SUS

FINISH:

2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

3.1 RATING: 1.8A(PIN1&5) , 0.5A(PIN2&3&4)

3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 VAC

3.3 CONTACT RESISTANCE: 30 mΩ MAX.

3.4 INSULATION RESISTANCE: 1000 MΩ MIN.



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CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 04/22/20
DATE: 04/22/20
DATE: 04/22/20

MAT'L
FINISH
SCALE
SHEET NO.

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
MICRO USB 5P B TYPE 沉板 板上
H 1.42 IPX7
1 : 1
1 of 2

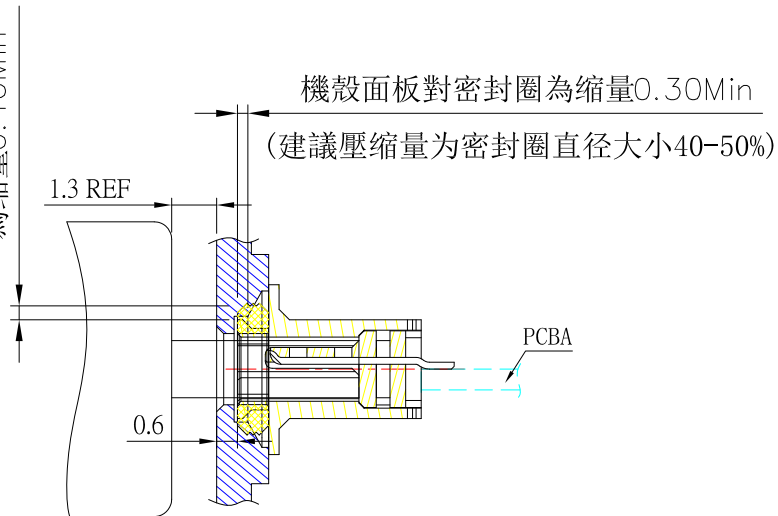
MRUSB-5B-WP11-x-S382
MRUSB-5B-WP11-x-S382

SIZE
A4
VER
R4

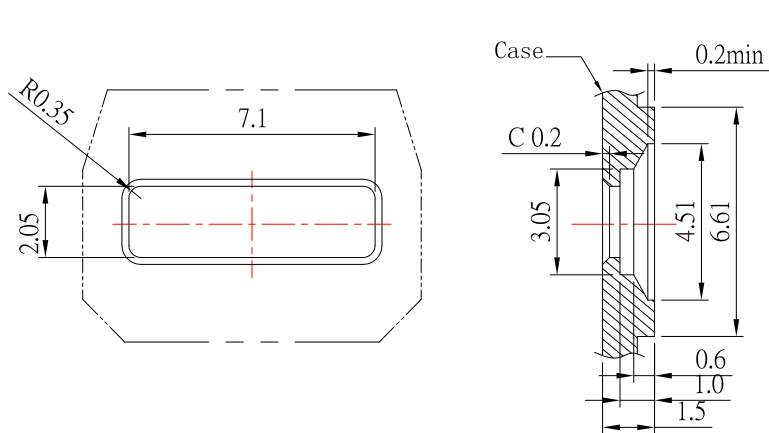
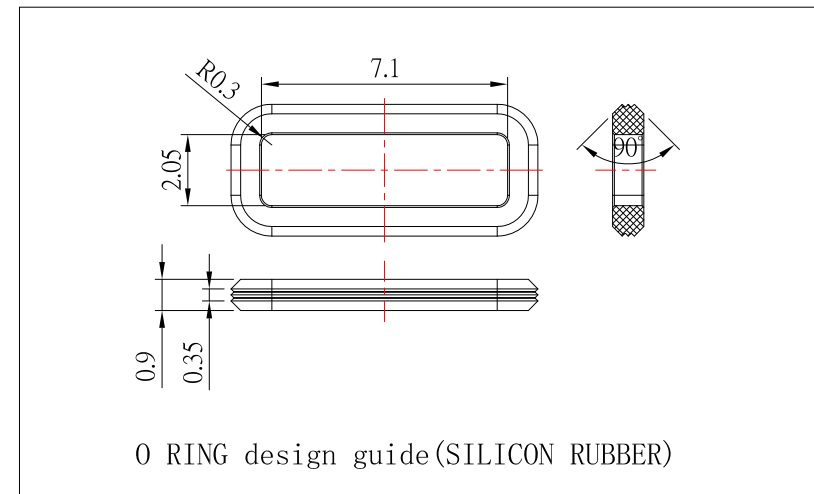
IPX7



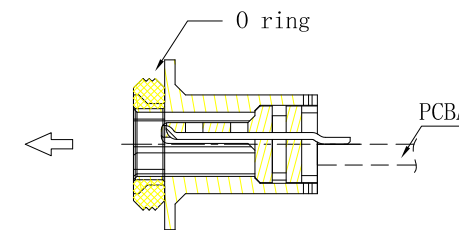
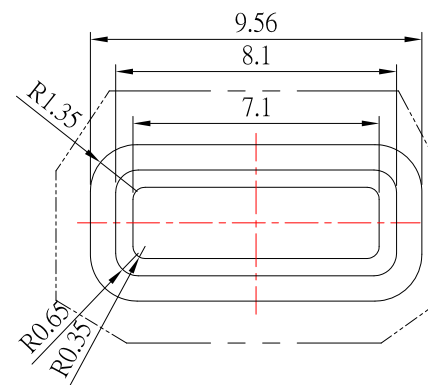
機殼面板對密封圈
為縮量0.40Min



COMPRESSION RATIO TO BE 40%-50%



RECOMMENDED OPEN DIMENSION OF CASE



Assembly direction



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CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED:

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 04/22/20
DATE: 04/22/20
DATE: 04/22/20

MATL
FINISH
SCALE: 1 : 1
SHEET NO. 2 of 2

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
MICRO USB 5PF B TYPE 沉板 板上
H 1.42 IPX7
MRUSB-5B-WP11-x-S382
MRUSB-5B-WP11-x-S382

SIZE: A4
VER: R4